

In re the Application of: Koji NOZAKI et al.

Group Art Unit: 1752

Application Number: 10/623,679

Examiner: Amanda C. Walke

Filed: July 22, 2003

Confirmation Number: 5083

For:

RESIST PATTERN THICKENING MATERIAL, RESIST

PATTERN AND PROCESS FOR FORMING THE SAME, AND

SEMICONDUCTOR DEVICE AND PROCESS FOR

MANUFACTURING THE SAME

Attorney Docket Number:

030891

Customer Number:

38834

RESPONSE

Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450 July 6, 2007

Sir:

This paper is filed in response to the Office Action dated February 8, 2007, the response due date extended to July 8, 2007 by a two-months Extension of Time.

Remarks begin on page 2 of this paper.